



## **Plasma Dicing – Latest Developments**

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The Plasma Dicing process employs the Bosch etch process to control the vertical, anisotropic profile to dice through the wafer. The etch process delivers superior dicing quality versus blade or laser dicing, eliminating the mechanical and thermal stress which can have great impact on the reliability of devices, and eliminating the dicing constraints for more efficient wafer design layouts and new devices. The latest developments in the technology include the capability doing plasma dicing on tape frame without damaging dicing tape or frame and very high selectivity to silicon to reduce wafer preparation costs.

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